

EUREKA: A Industry EUV Research Center at LBNL

Patrick Naulleau

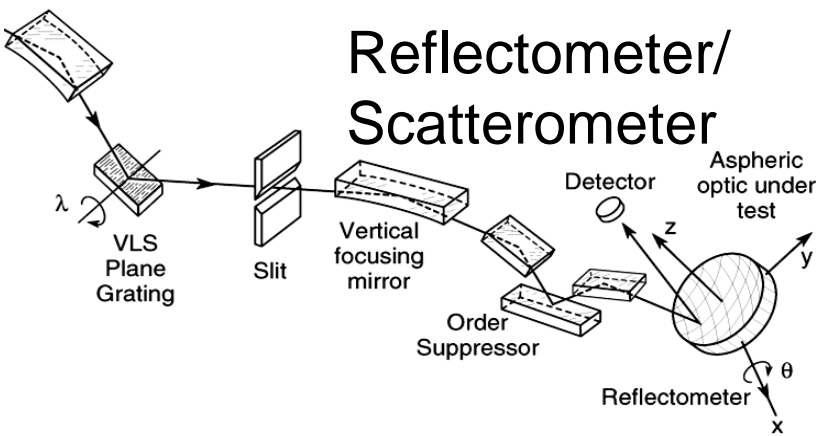
Center for X-ray Optics

Lawrence Berkeley National Laboratory

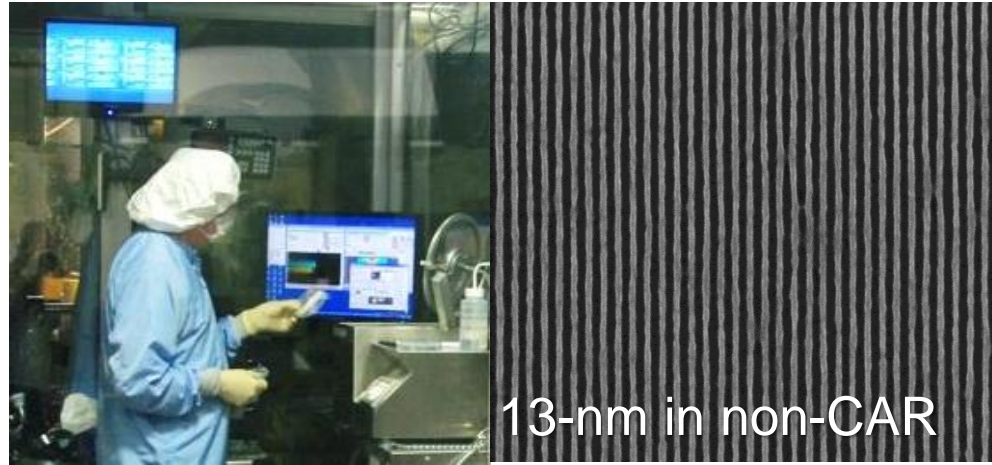
Outline

- Reflectometry
- Mask review: SHARP
- 0.3-NA MicroExposure: MET3
- 0.5-NA MicroExposure: MET5
- Other

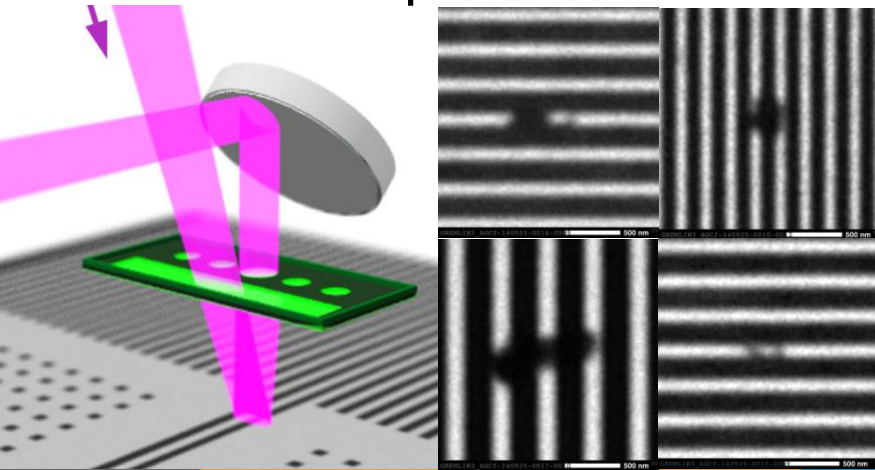
Cornerstone tools



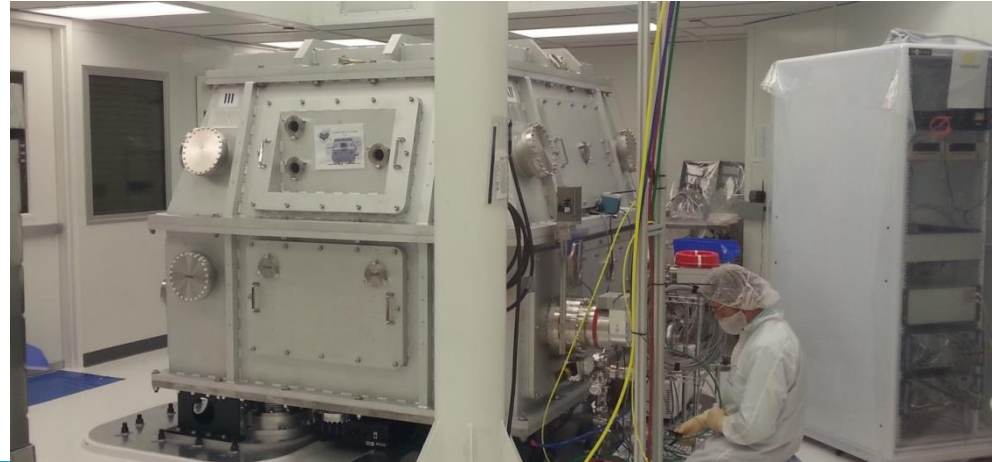
0.3-NA Litho



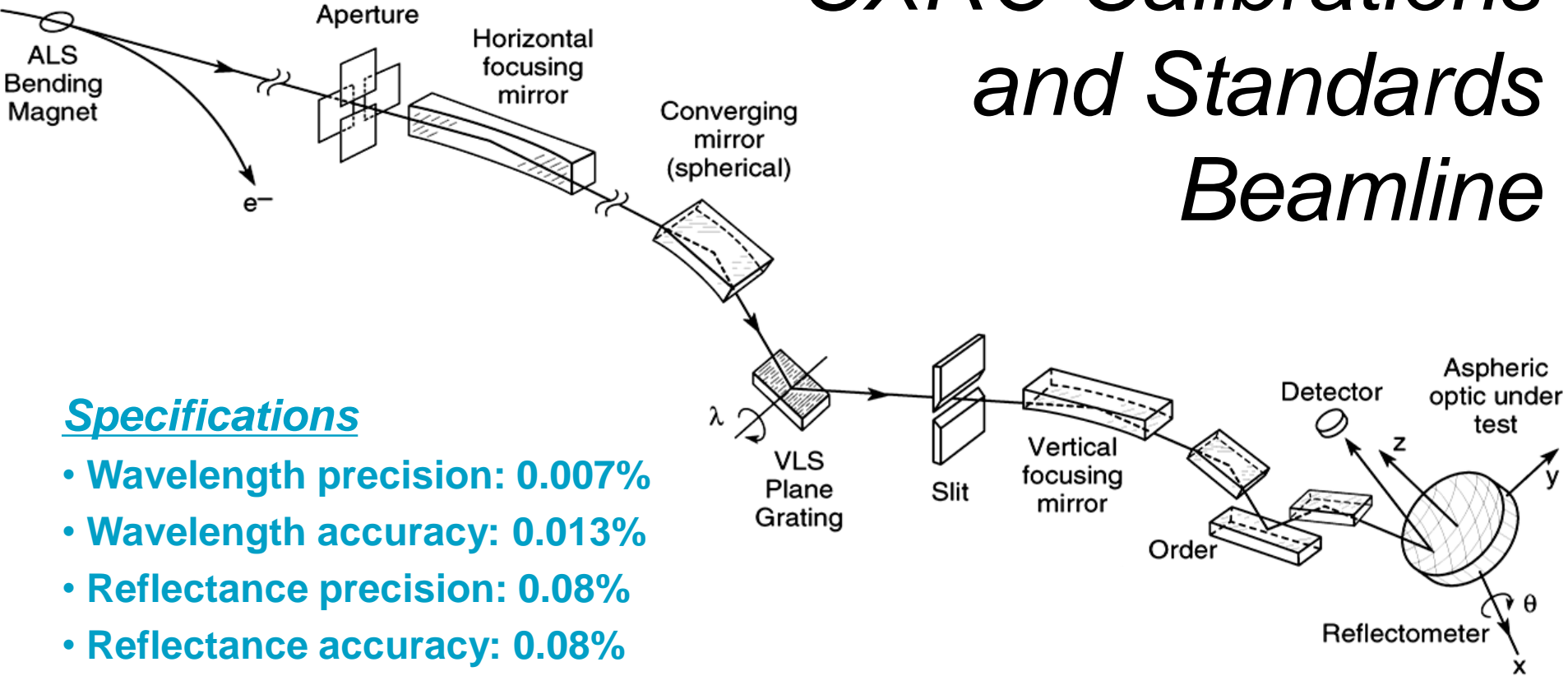
EUV AIMS up to 0.6 NA



0.5-NA Litho coming soon



CXRO Calibrations and Standards Beamline

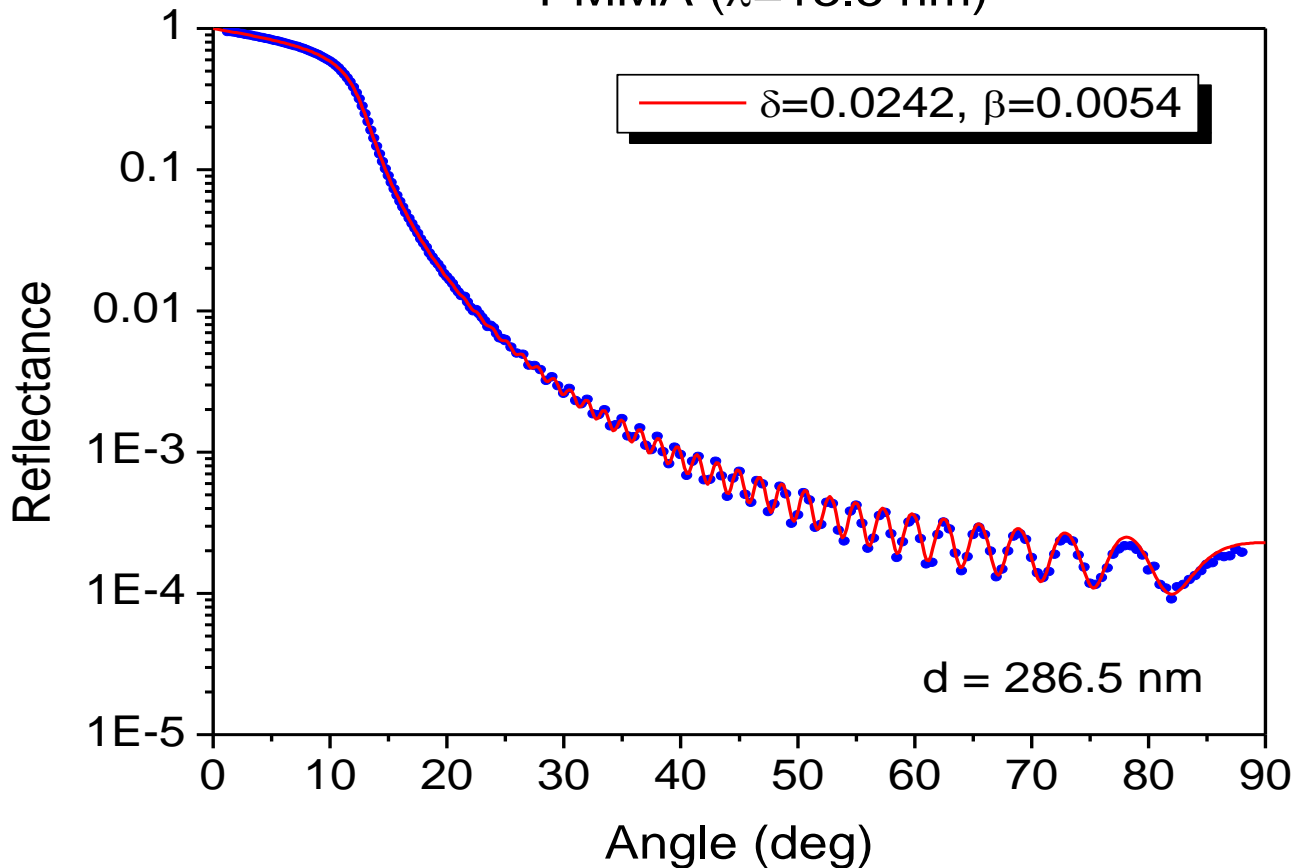


Specifications

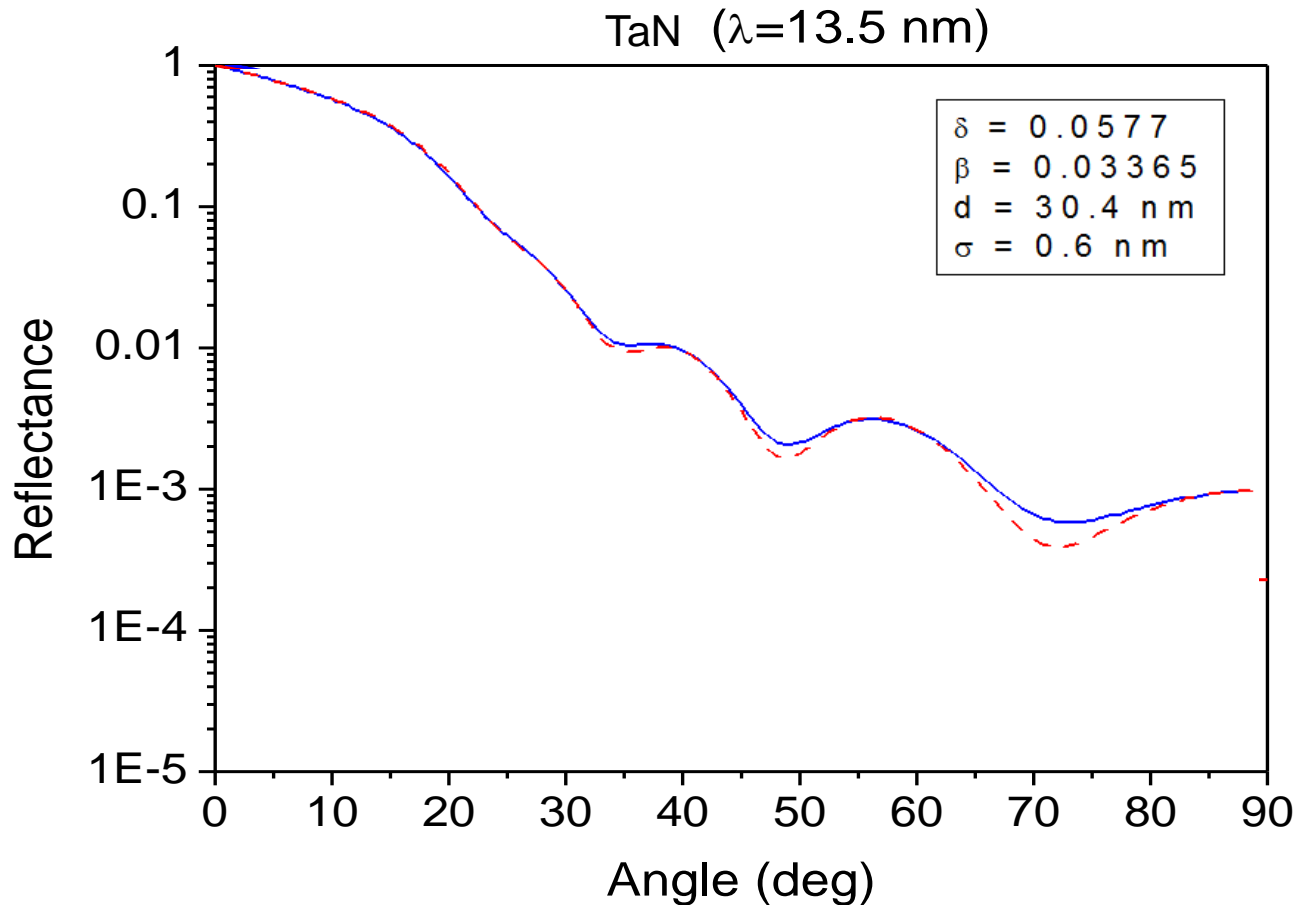
- Wavelength precision: 0.007%
- Wavelength accuracy: 0.013%
- Reflectance precision: 0.08%
- Reflectance accuracy: 0.08%
- Spectral purity: 99.98%
- Dynamic range: 10^{10}

High accuracy measurements of optical constants of EUV resist and mask materials

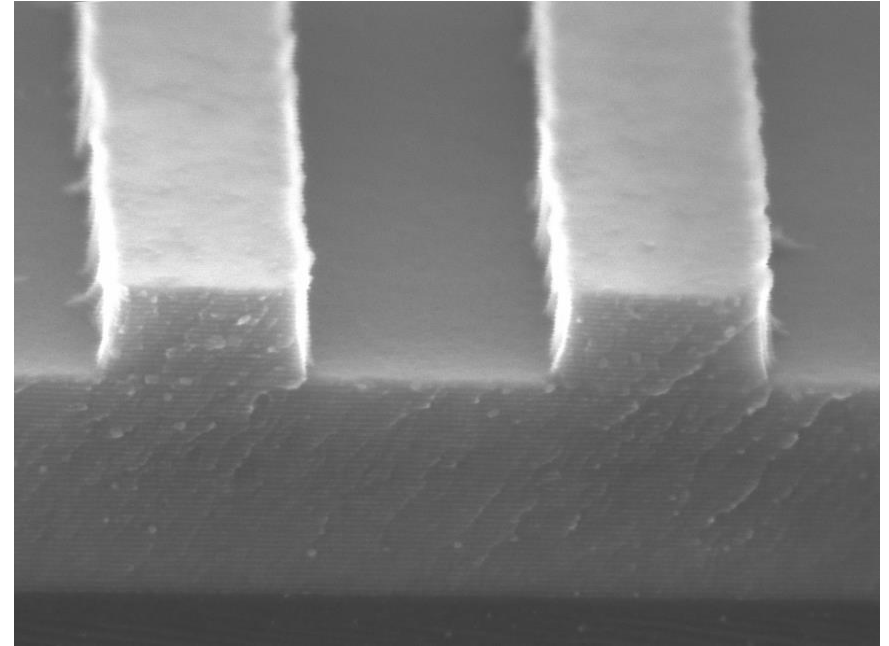
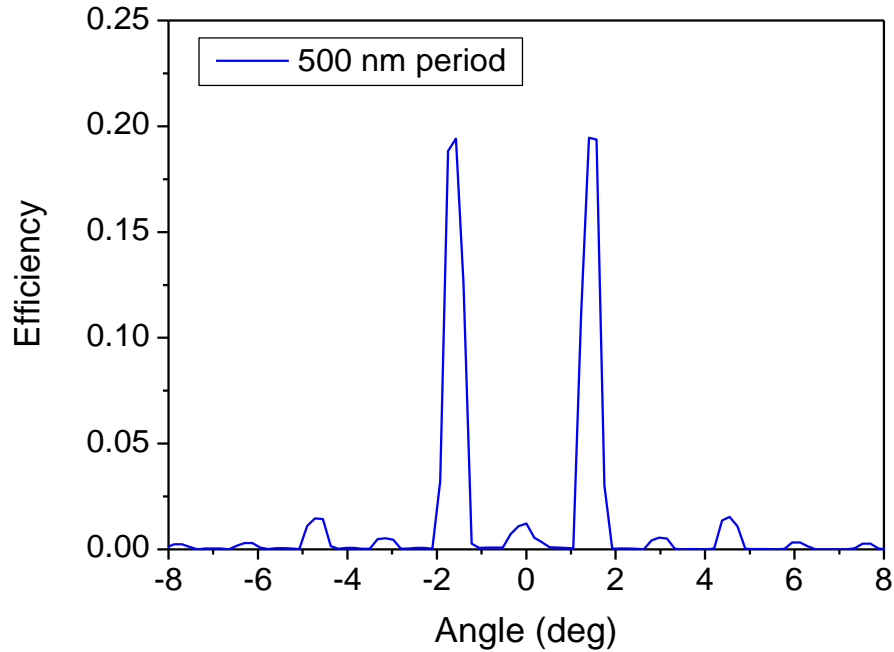
PMMA ($\lambda=13.5$ nm)



High accuracy measurements of optical constants of EUV resist and mask materials



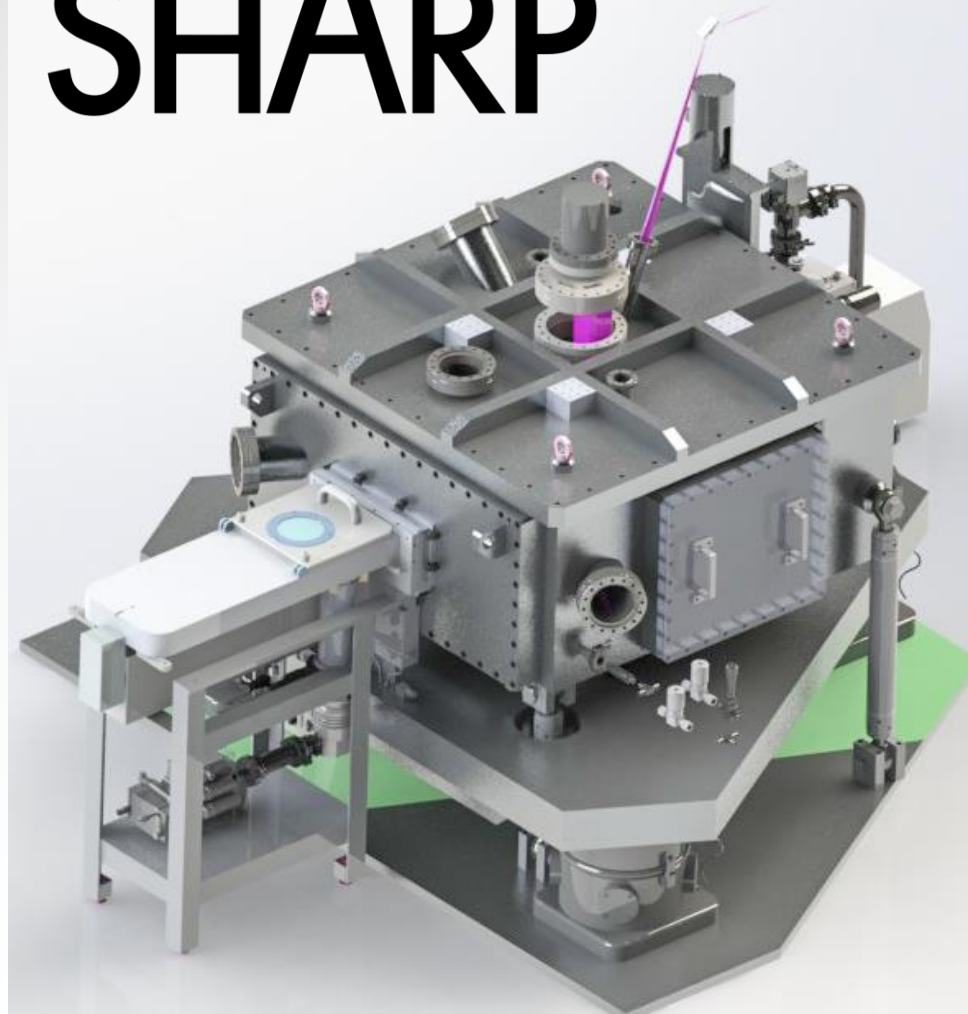
Diffraction characterization of EUV masks



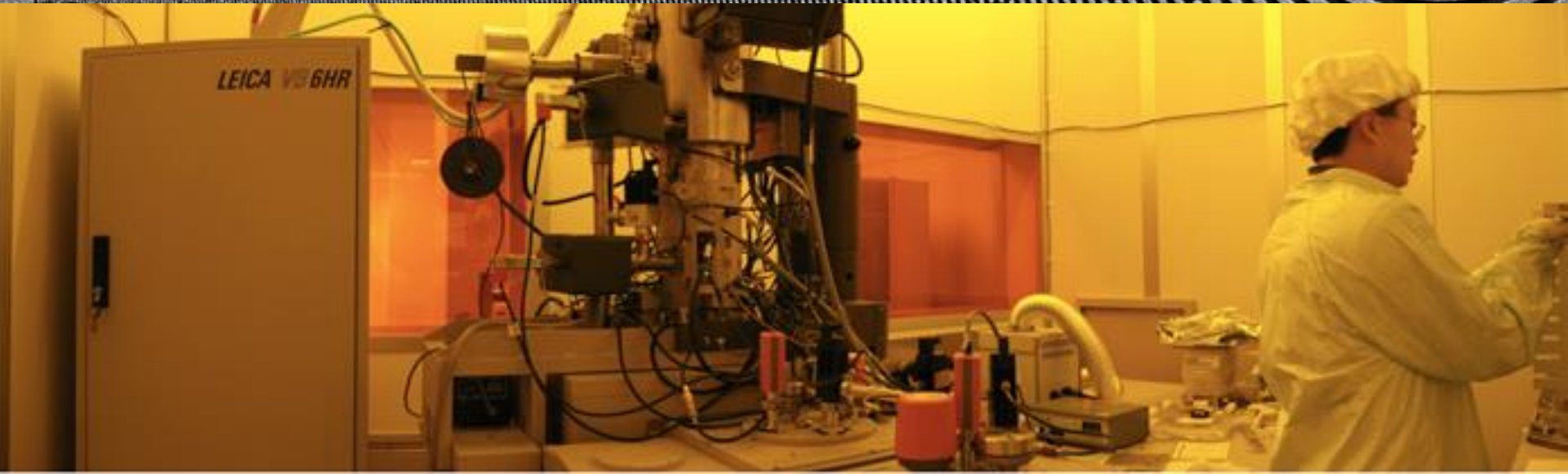
EUV High NA review tool

- **Optics:**
Zoneplate-lenses
- **Effective NA:**
0.250–0.625
- **Coherence:**
Programmable
- **Magnification:**
Variable
- **Imaging modes:**
Bright, Dark, Zernike
phase, DIC ...

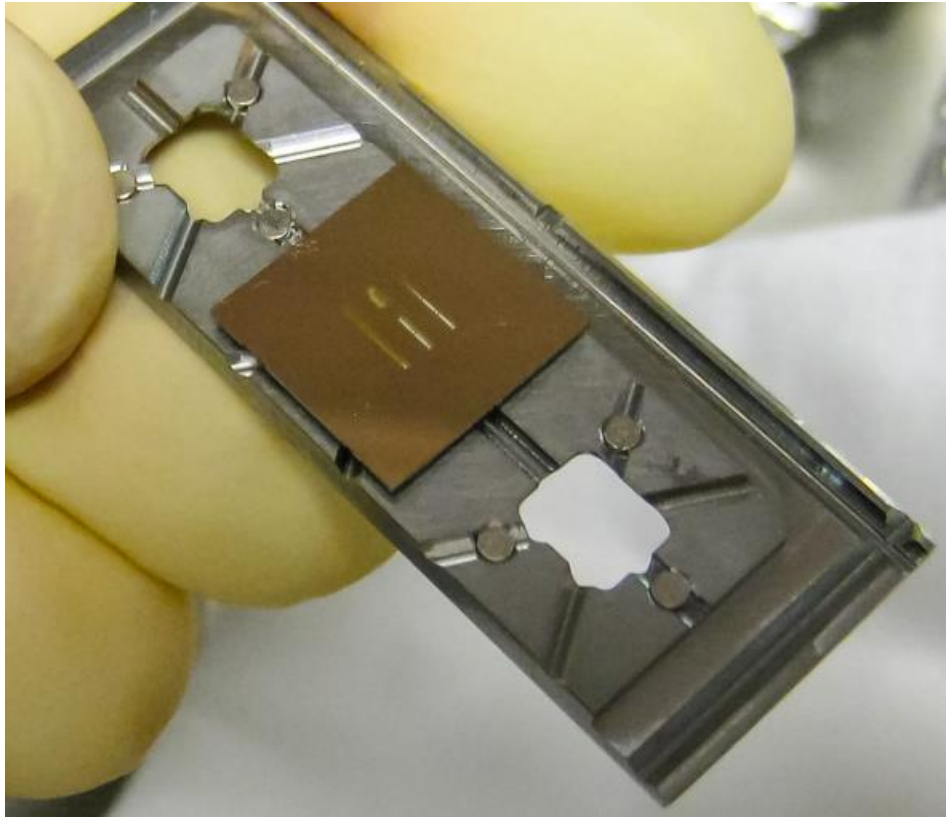
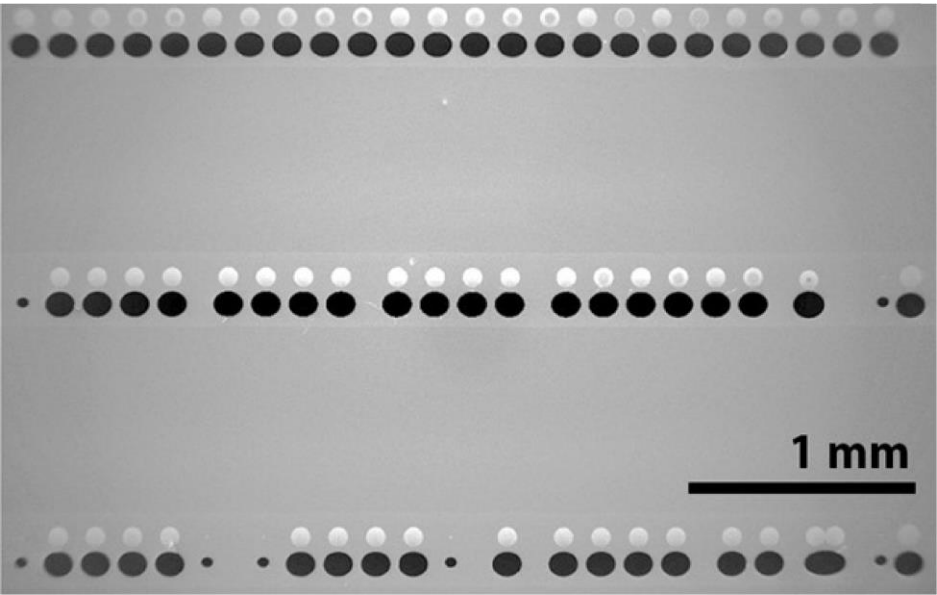
SHARP



Leverage CXRO world-leading zoneplate fabrication capabilities

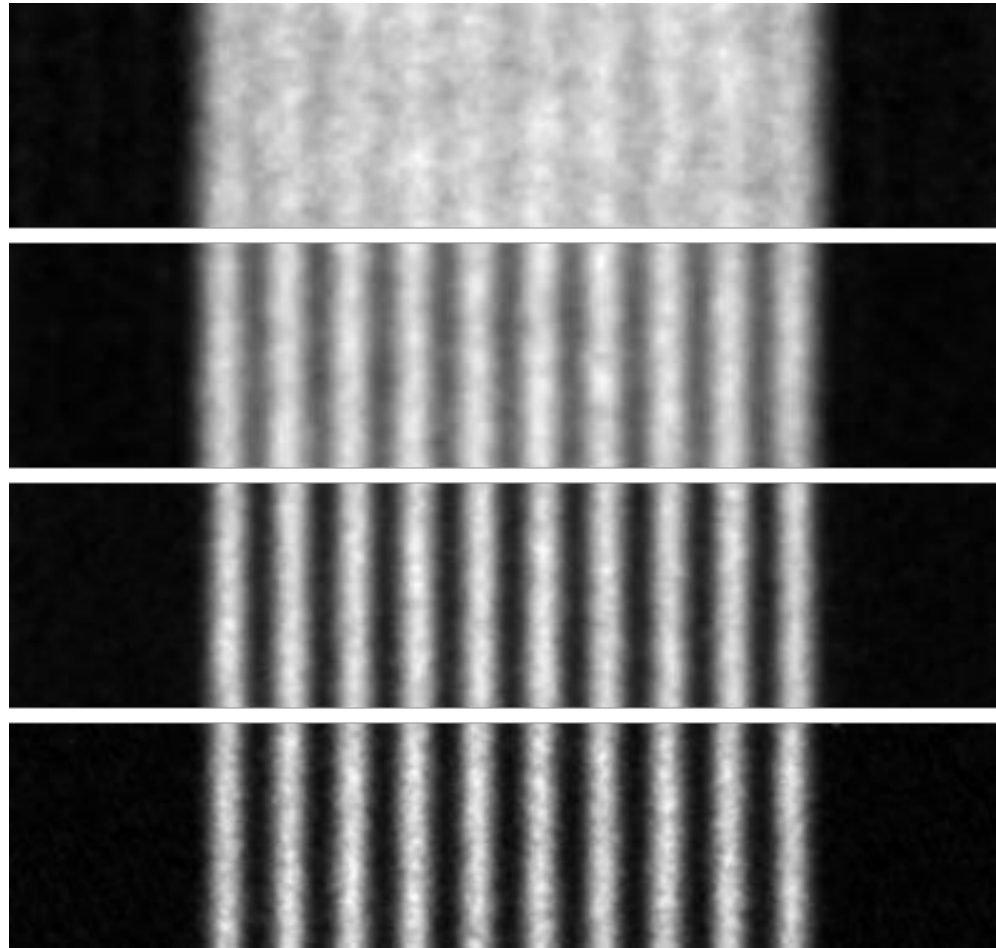


Select between hundreds of lenses on the fly



0.625 effective NA demonstrated

16-nm
code lines
(64-nm on
mask)

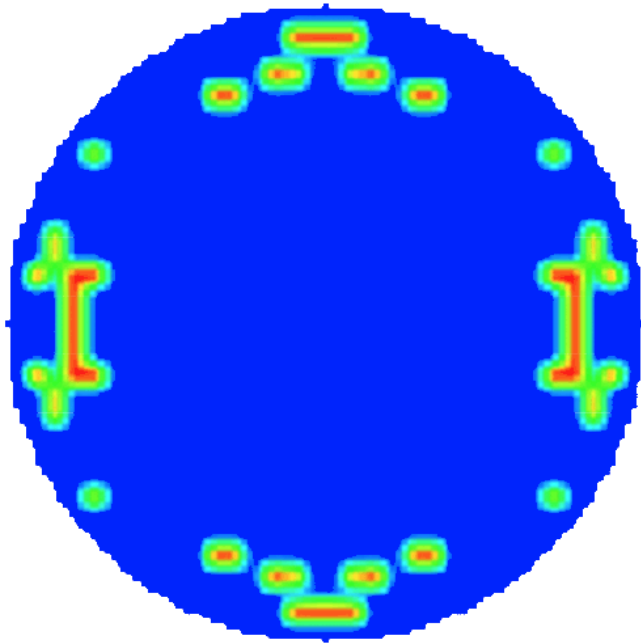


0.25 0.33 0.50 0.625

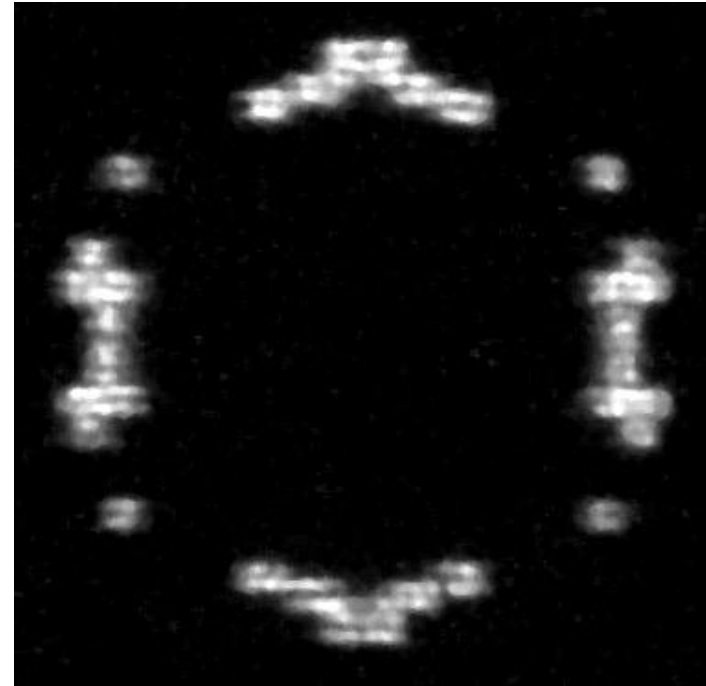
4xNA $\sigma = 0.8$

Freeform source capabilities

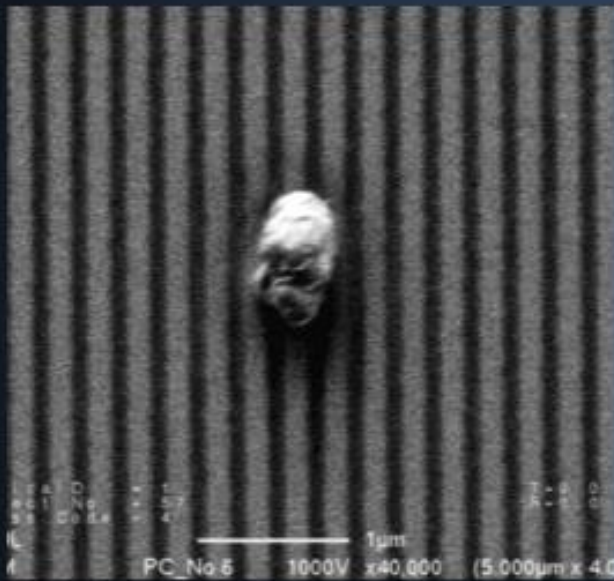
Target source
shape



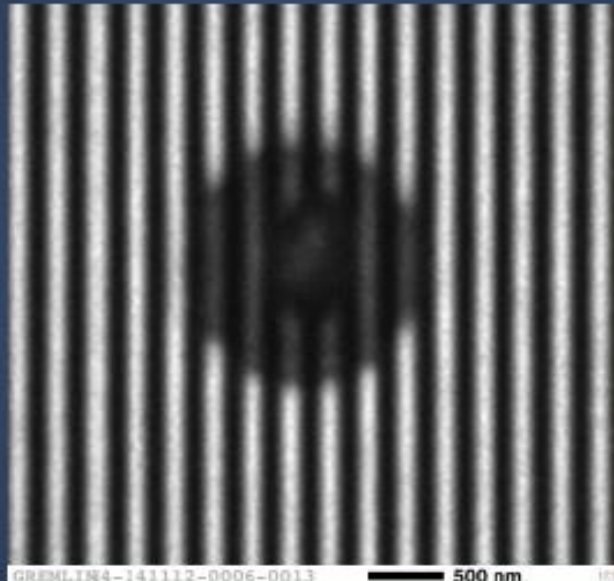
Measured
source shape



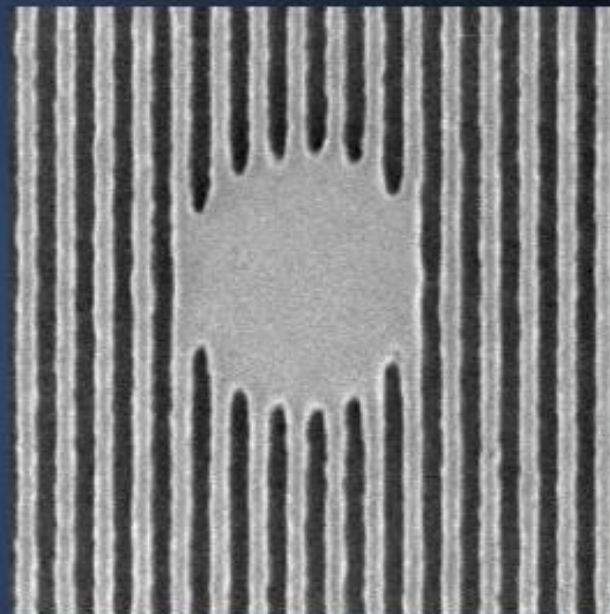
SHARP true to wafer print



Mask SEM



SHARP EUV

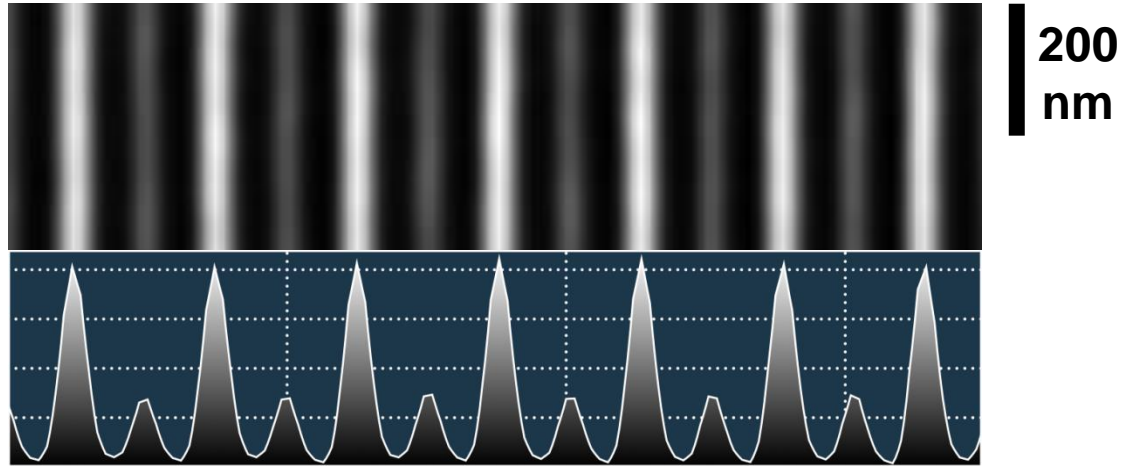


Wafer SEM

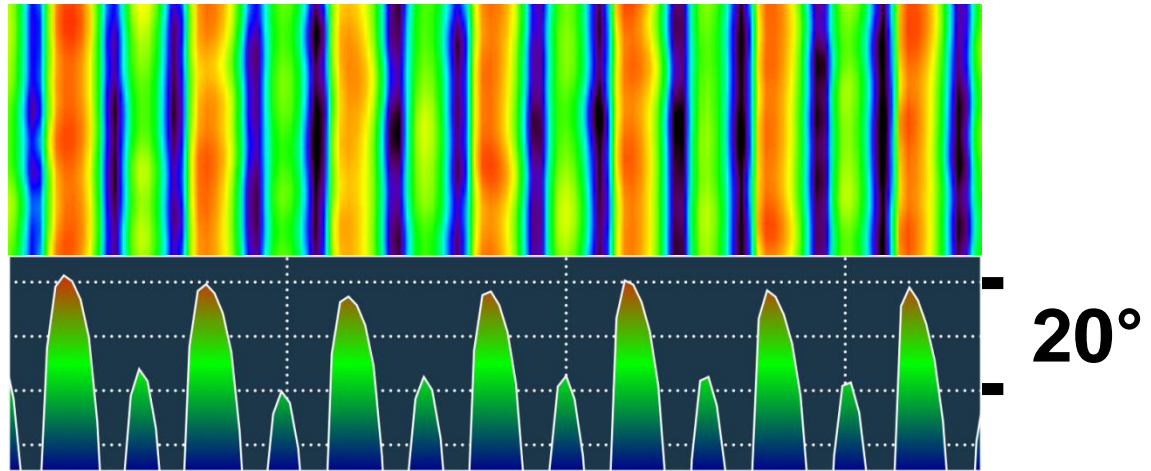
Quantitative phase

Resolving
SRAFS

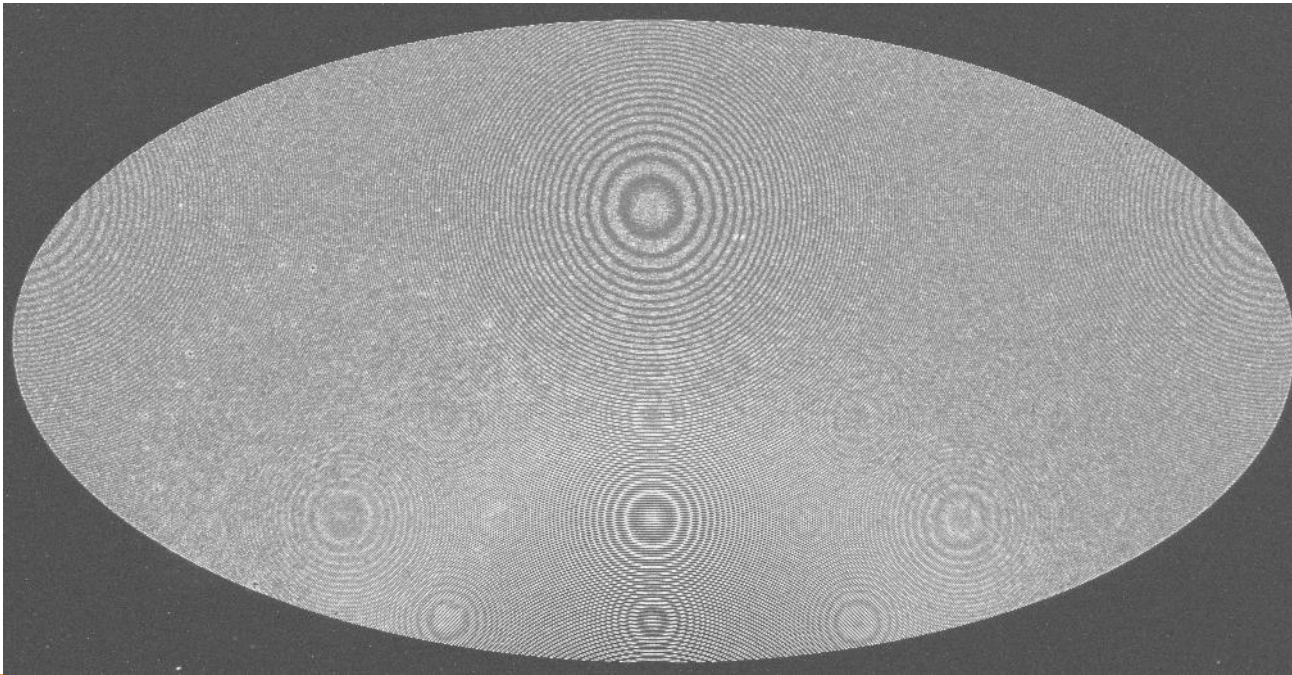
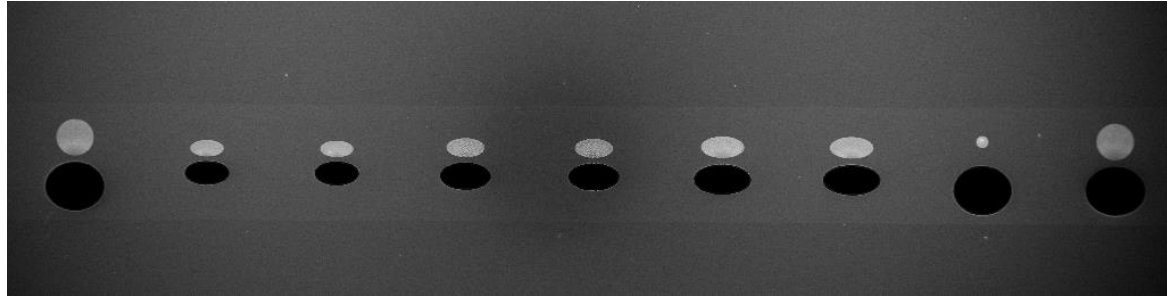
I

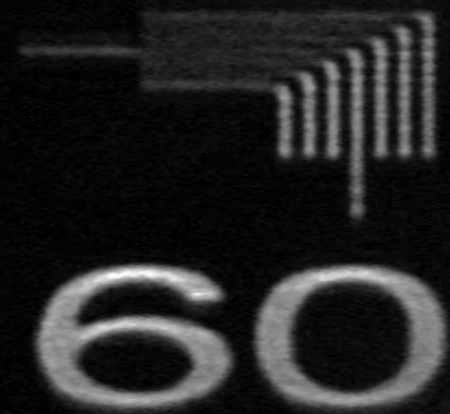


Φ

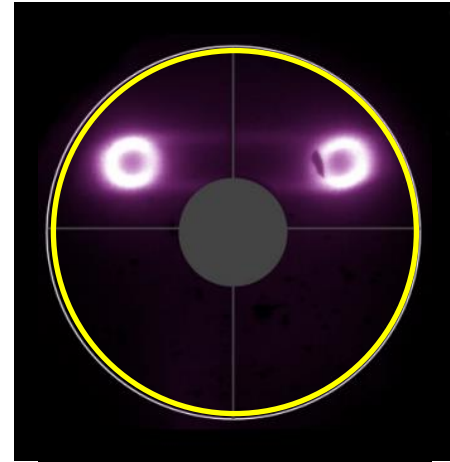
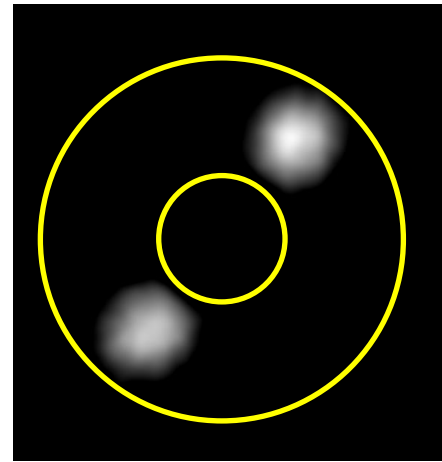
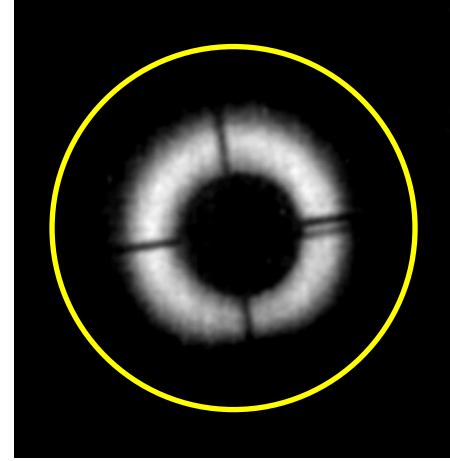
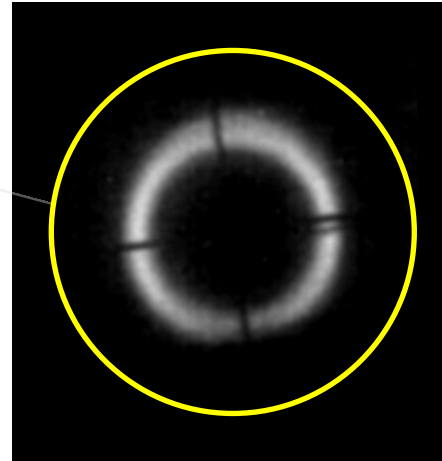
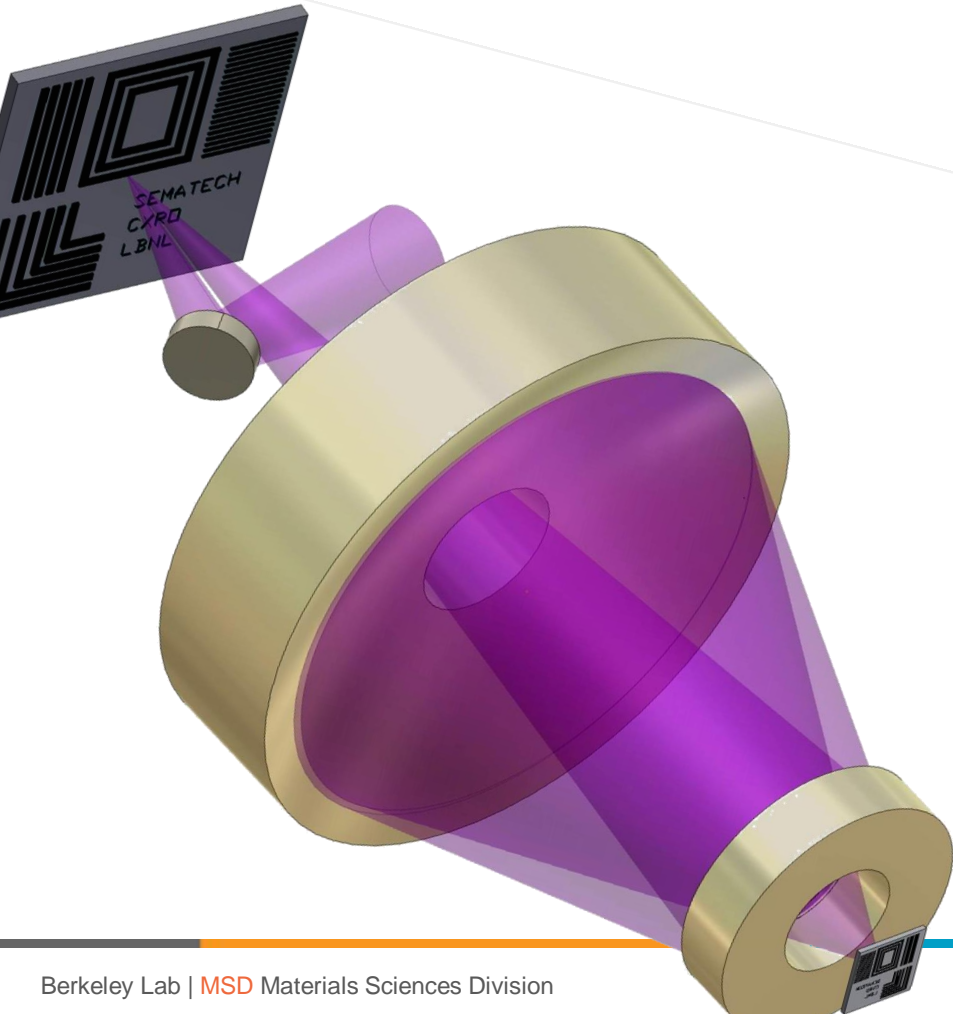


Anamorphic NA capabilities



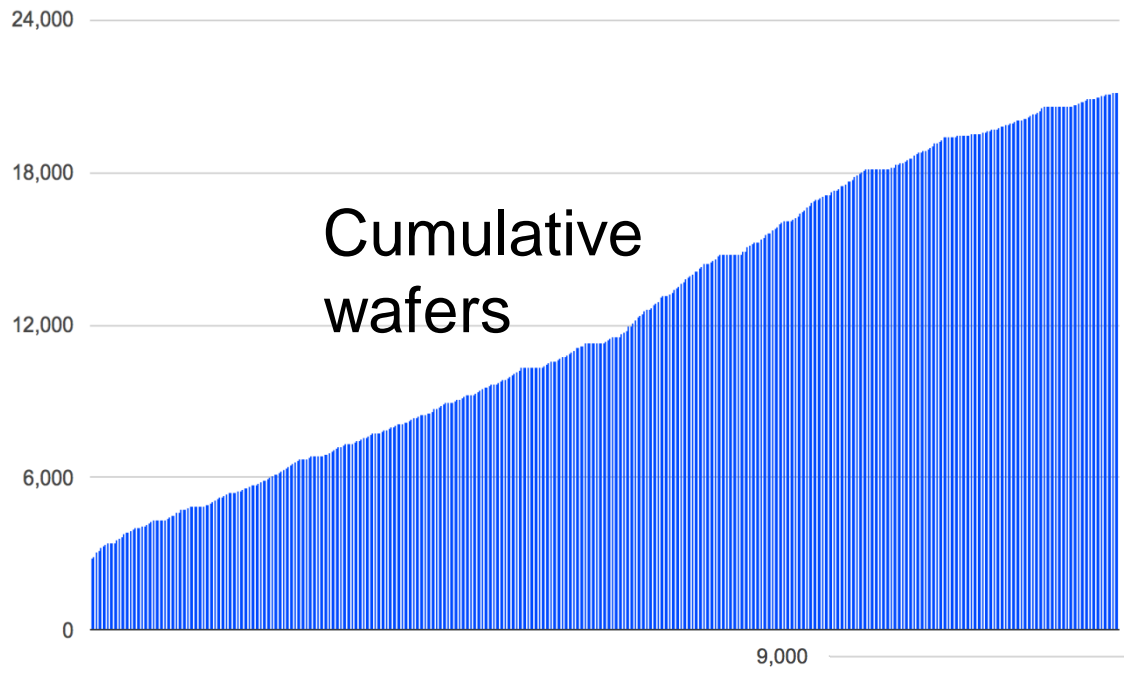


EUVV 0.3-NA MET

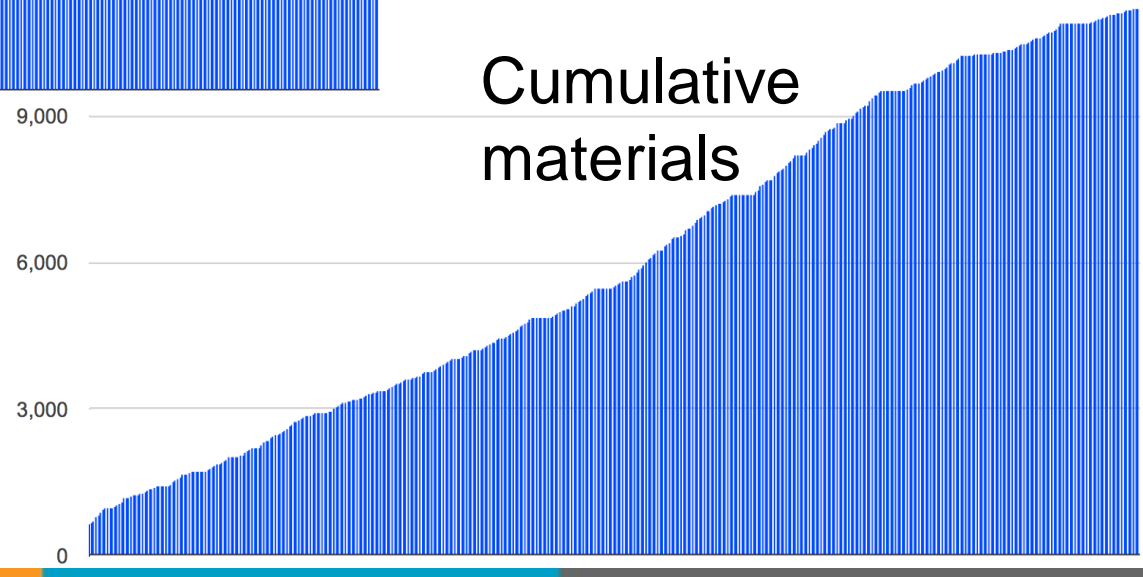


MET: engine for materials learning

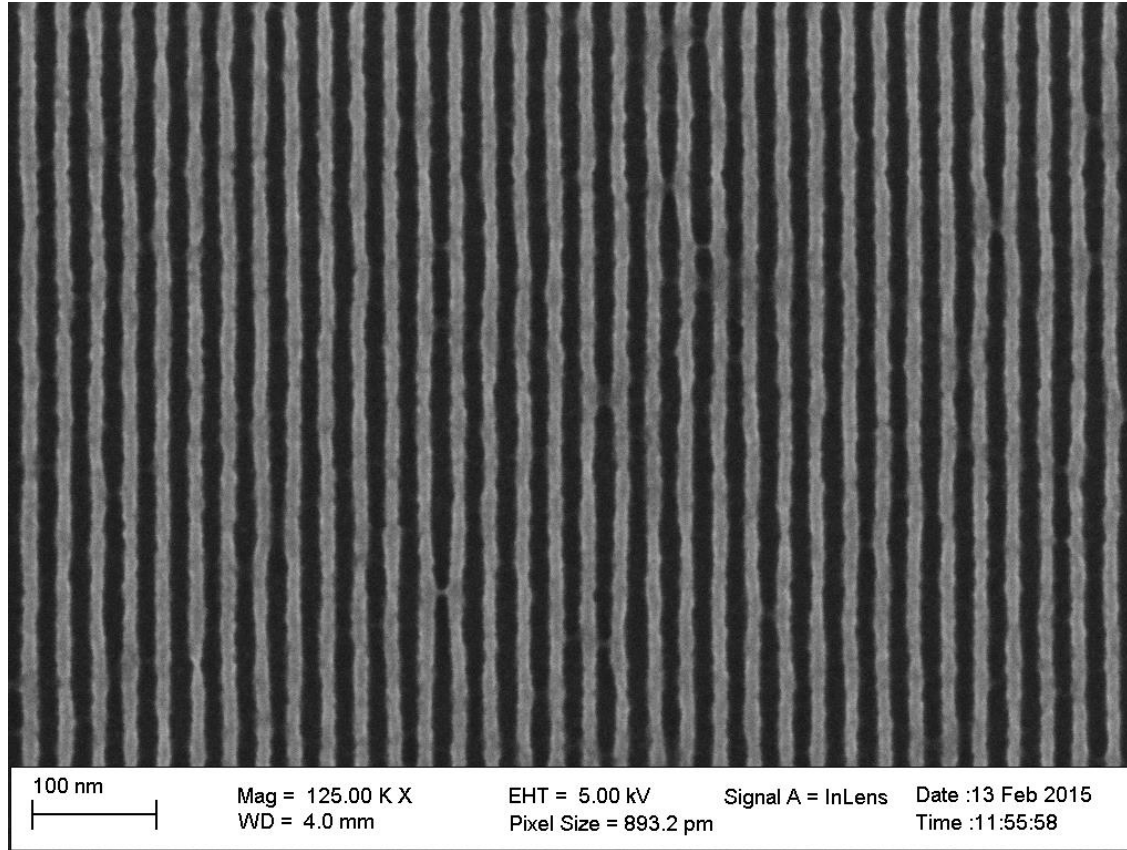
Cumulative
wafers



Cumulative
materials



13-nm patterning achieved in non-CA resist

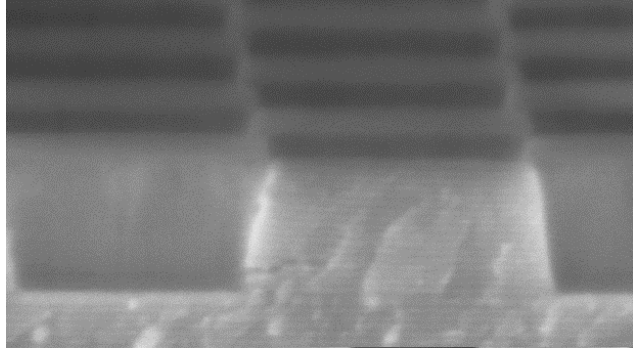


LWR
= 3.1 nm

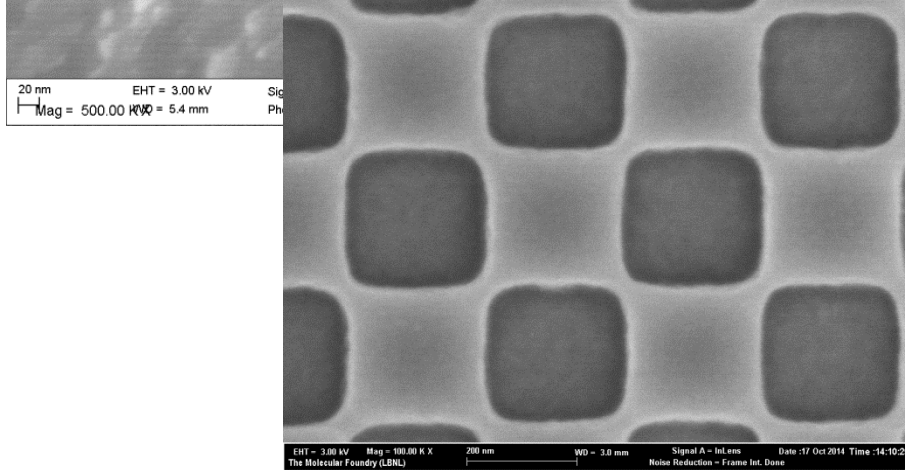


7x throughput gain on 25-nm contacts with PSM mask

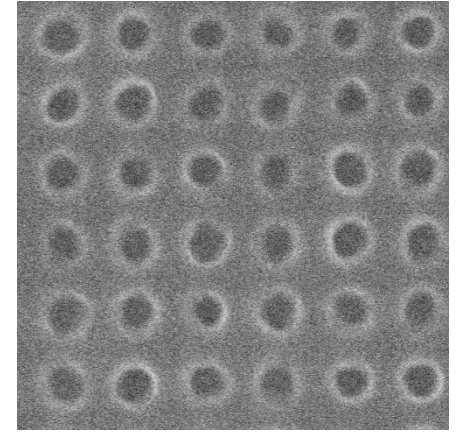
Checker PSM



Etched-ML mask

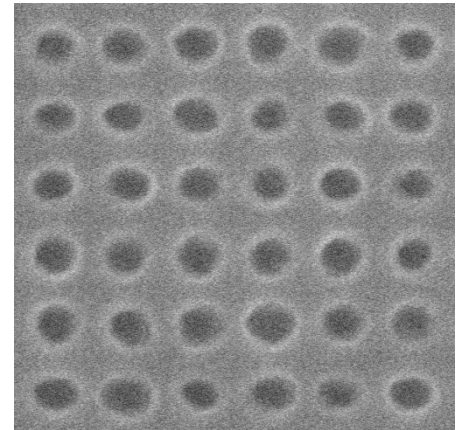


13
mJ/cm²



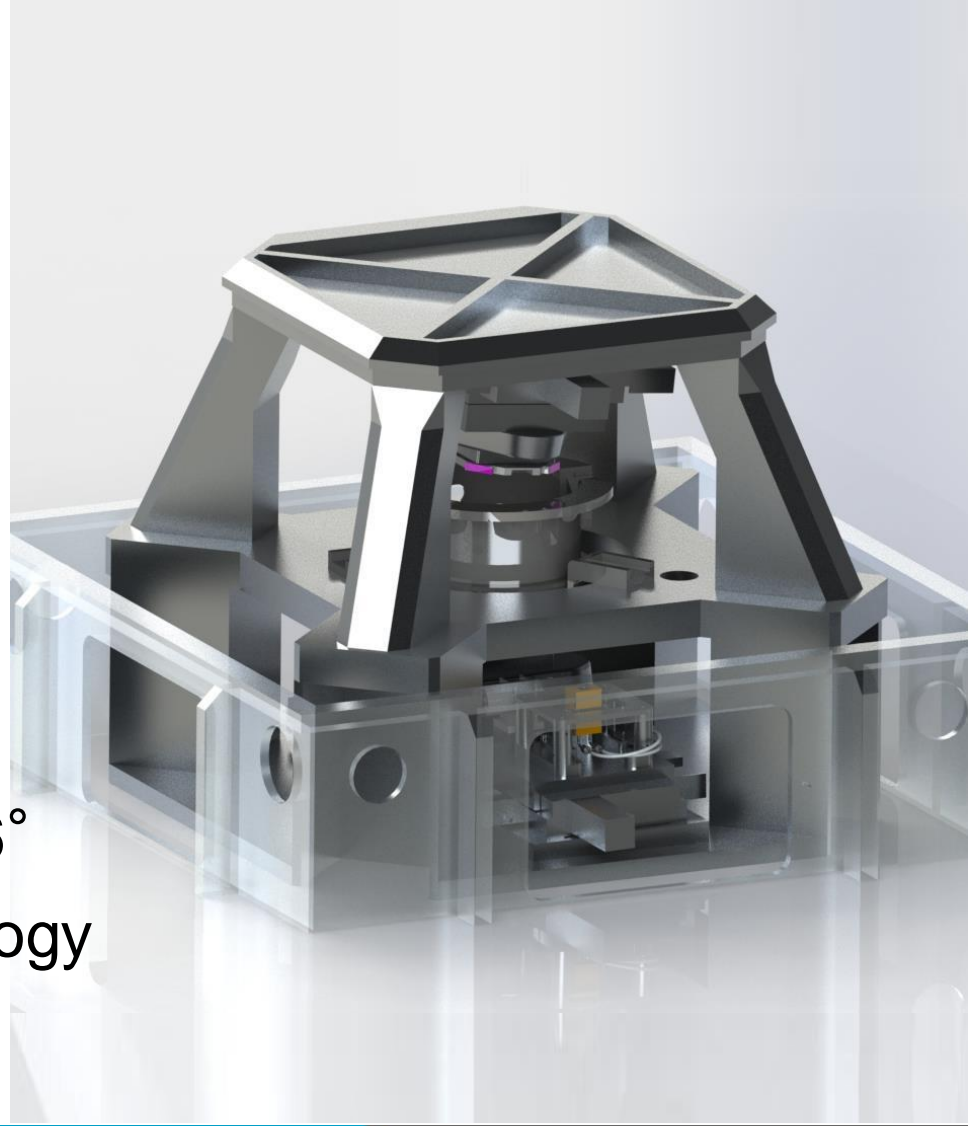
Absorber

94
mJ/cm²



MET5

- NA = 0.5
- Magnification = 5x
- Resolution limit = 8 nm
- Programmable pupil fill
- Mask angle of incidence = 6°
- Integrated wavefront metrology
- Robotic linked track

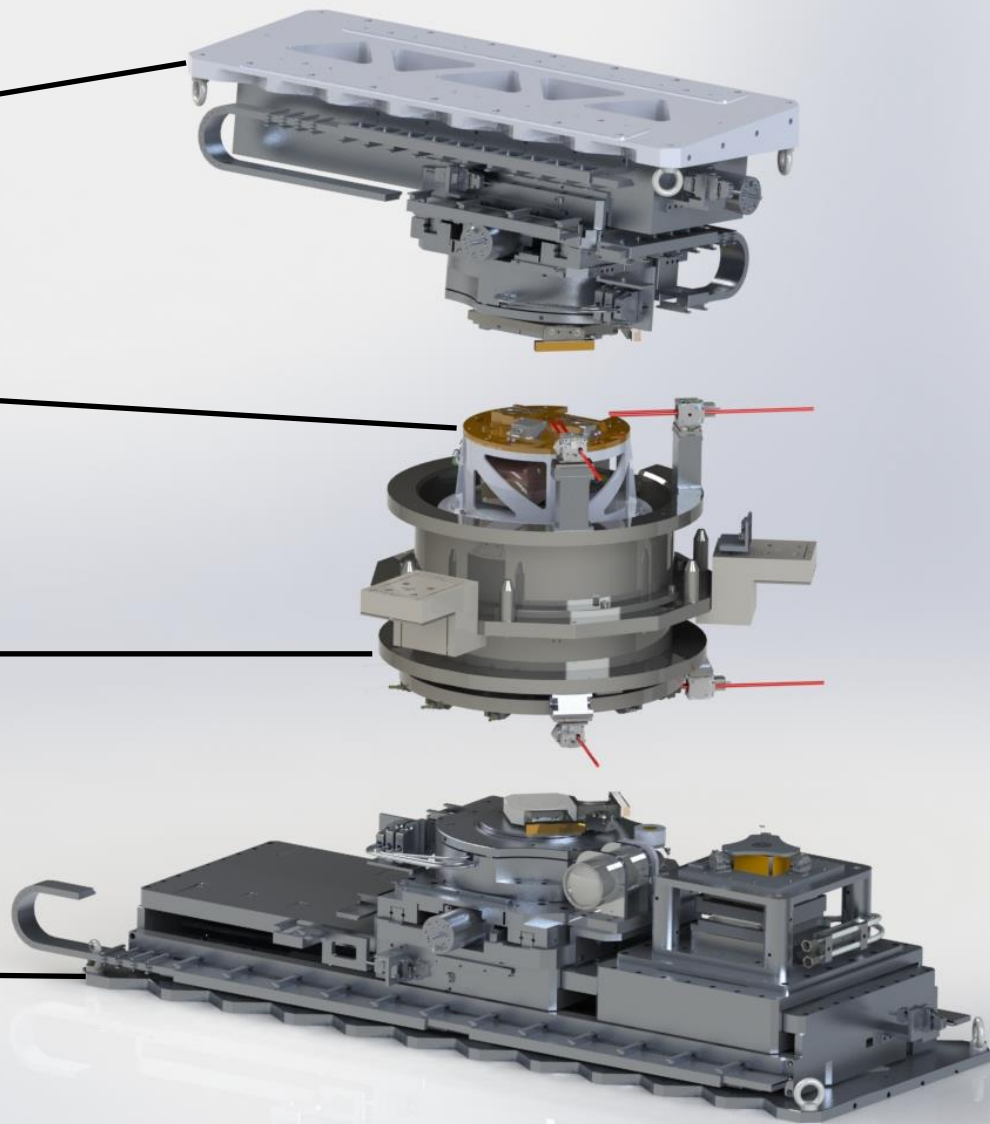


Reticle stage assembly

Projection optics box

Tool core metrology frame

Wafer stage assembly



7-axis reticle stage

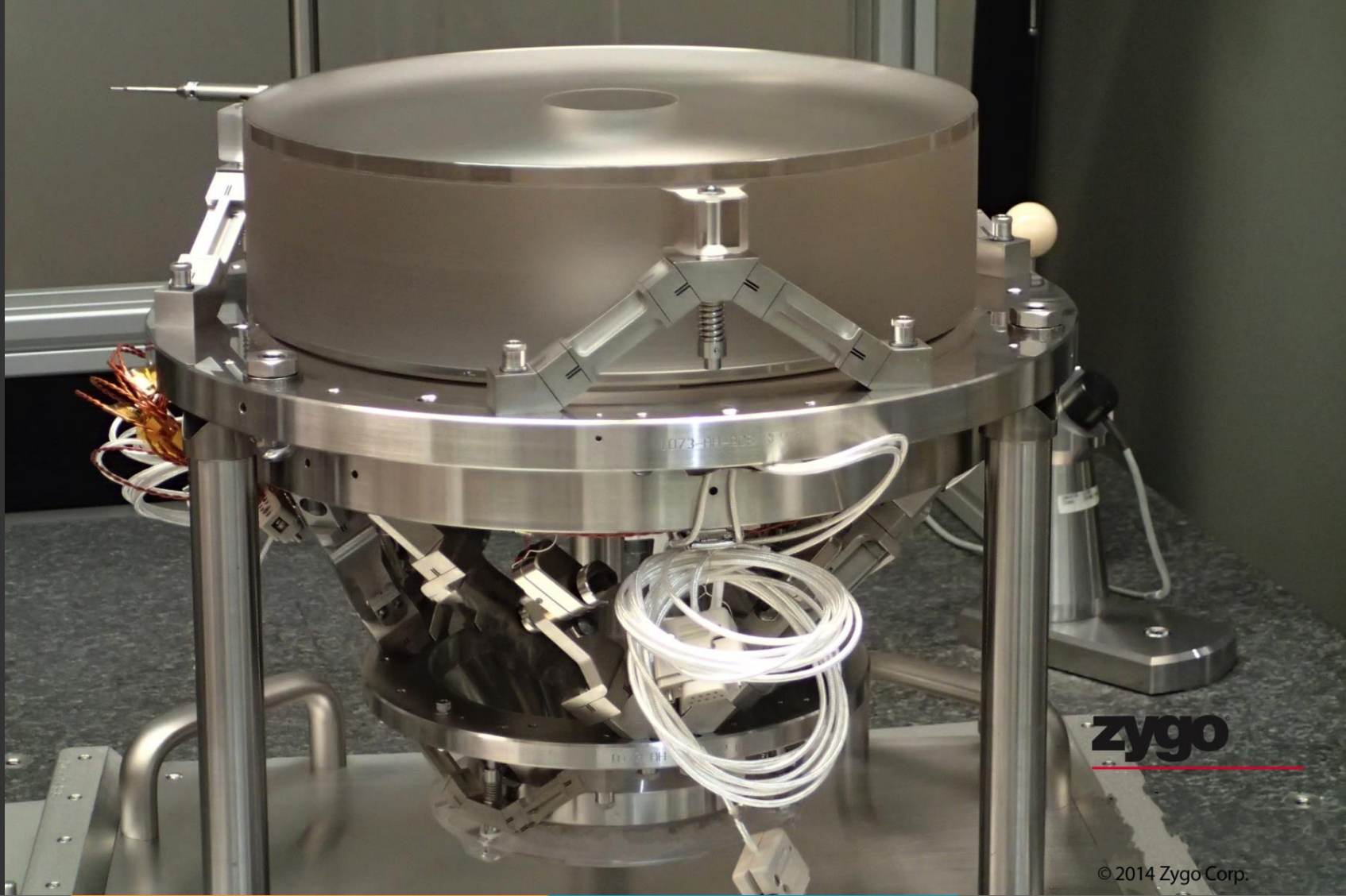
	Spec	Measured
XY Low freq. ($<2\text{Hz}$) PV	3 nm	0.92 nm
XY High freq. ($>0.5\text{Hz}$) RMS	2 nm	0.33 nm
Z Low freq. ($<2\text{Hz}$) PV	10 nm	1.7 nm
Z High freq. ($>0.5\text{Hz}$) RMS	3 nm	0.61 nm



5-axis wafer stage/ 2-axis LSI carriage

	Spec	Measured
XY Low freq. (<2Hz) PV	3 nm	0.51 nm
XY High freq. (>0.5Hz) RMS	1 nm	0.65 nm
Tip/Tilt RMS	18 mrad	0.15 mrad
Z Low freq. (<2Hz) PV	10 nm	1.5 nm
Z High freq. (>0.5Hz) RMS	3 nm	0.42 nm





1073-BH-103

zygo

© 2014 Zygo Corp.

Individual mirrors better than spec

M1

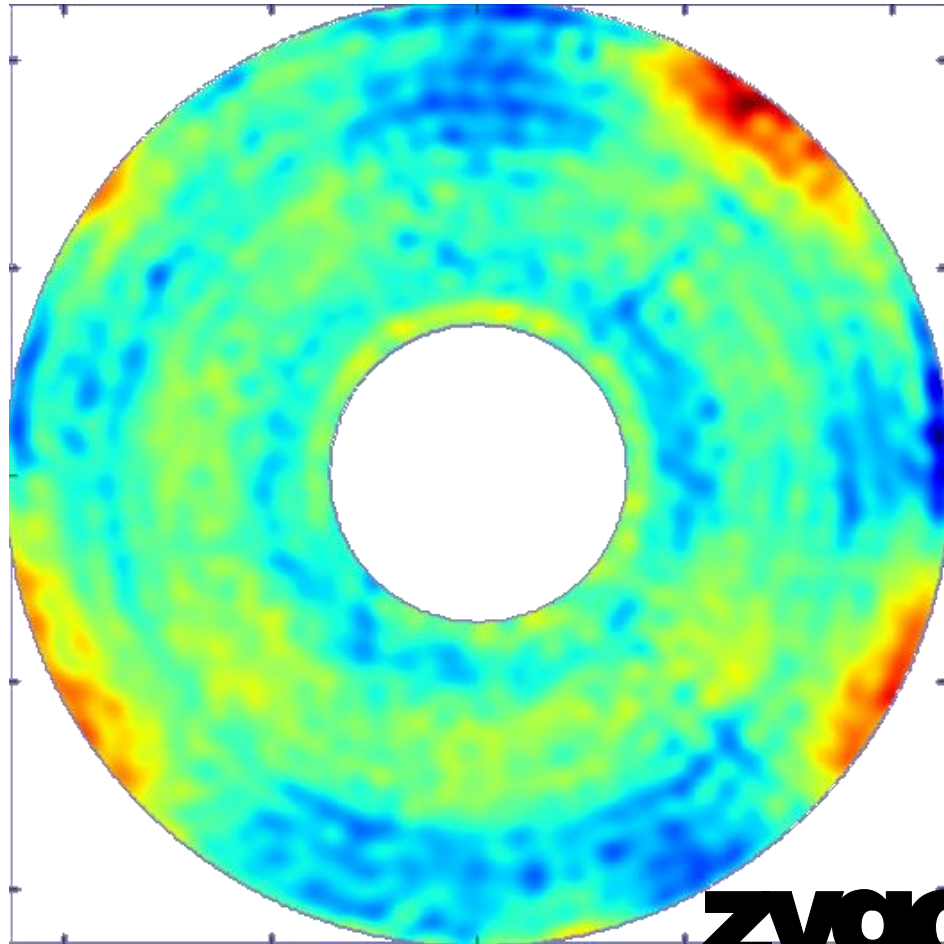
	Range	Specification	Result
Figure	CA – 3mm	< 0.1nm rms	0.04 nm rms
Flare	3mm – 0.43um	< 0.17nm rms	0.12 nm rms
HSFR	1um – 10nm	< 0.15nm rms	0.08 nm rms

M2

	Range	Specification	Result
Figure	CA – 8mm	< 0.1nm rms	0.08 nm rms
Flare	8mm – 1.2um	< 0.17nm rms	0.14 nm rms
HSFR	1um – 10nm	< 0.15nm rms	0.09 nm rms

Predicted POB EUV flare = 2.86%

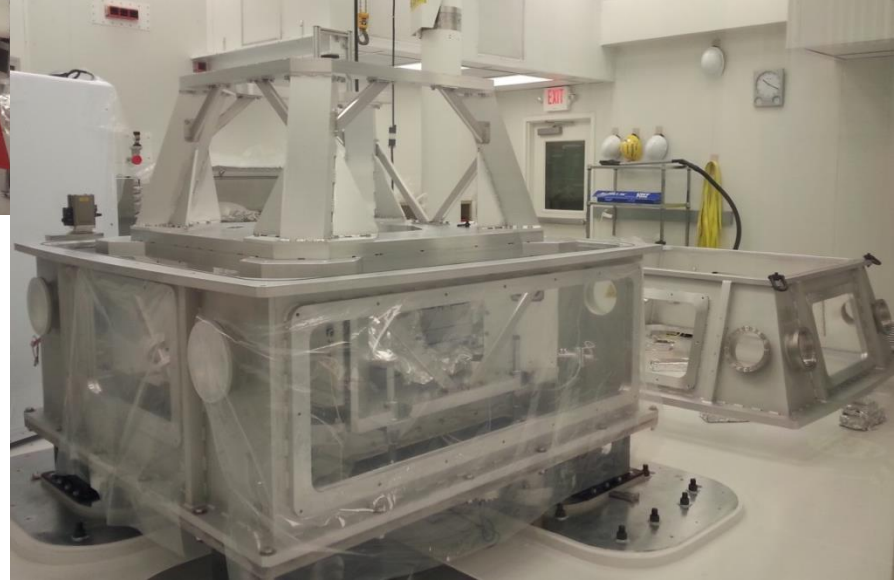
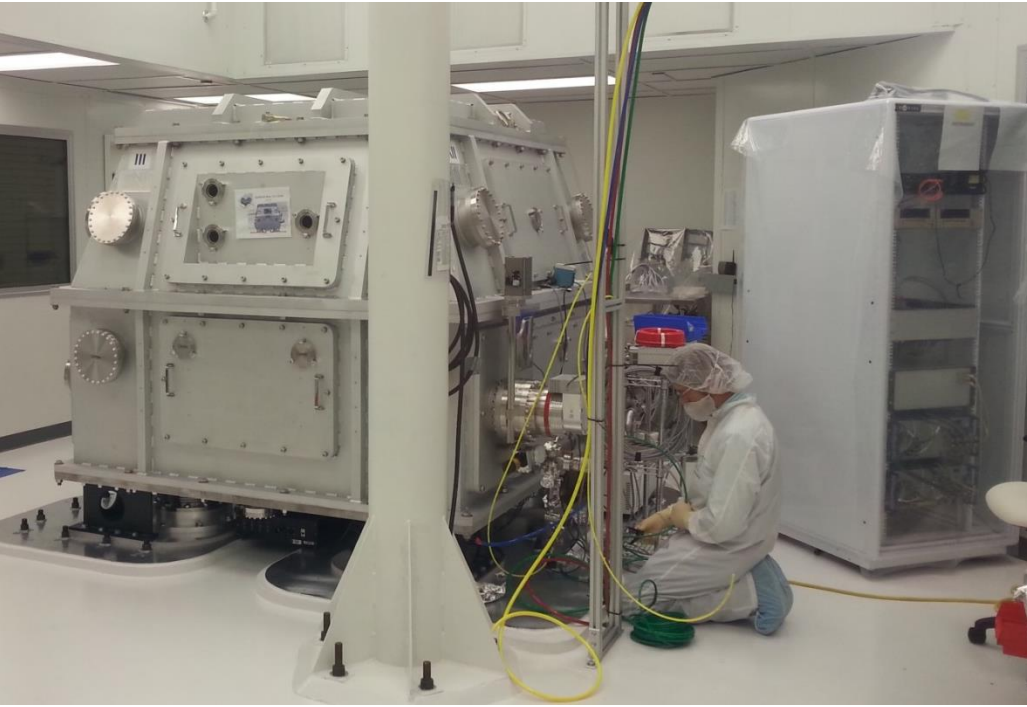
System wavefront 2x better than spec



Reticle field point (um)	WFE @ 30cycles across aperture (nm rms)
0, 0	0.21 (spec=0.5)
75, 500	0.43 (spec=1.0)
75, -500	0.41 (spec=1.0)
-75, -500	0.34 (spec=1.0)
-75, 500	0.36 (spec=1.0)

zygo[®]

Platform integration nearly complete

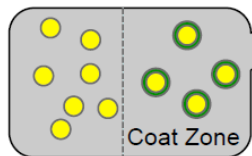
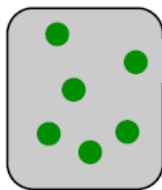


The logo for MET5, featuring a purple arch above the text "MET5". The "MET" is in black and the "5" is in purple.

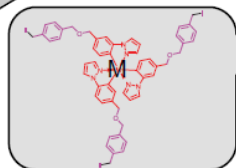
Potential expansion of EUREKA program resources

Instrumentation for direct characterization of EUV radiation chemistry

Nebulized polymeric resist condenses to particles



Inorganic nanoparticle resists coated in-situ with resist materials



Molecular resist

EUV

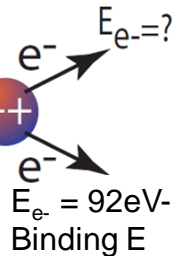
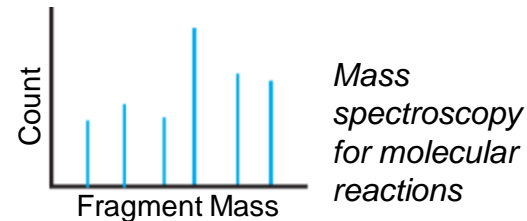
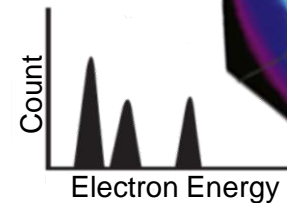


Photo-electron imaging for energy and count



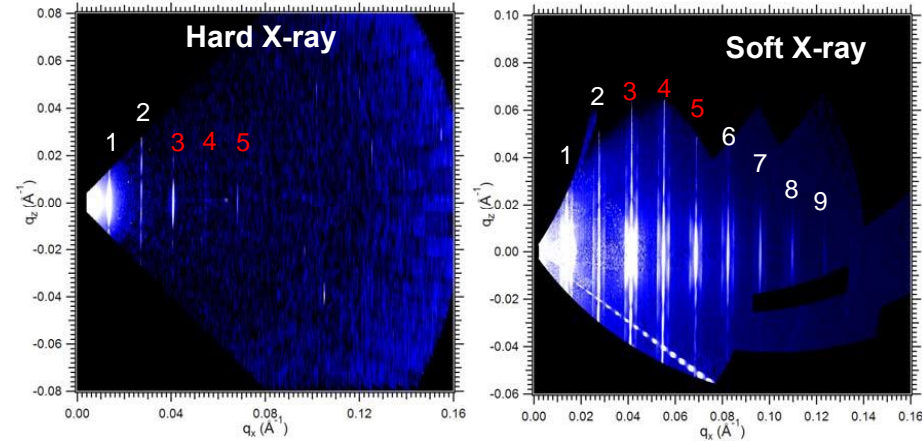
1: Introduce materials as molecular or nanoparticle beam

2: Irradiate with EUV or electrons

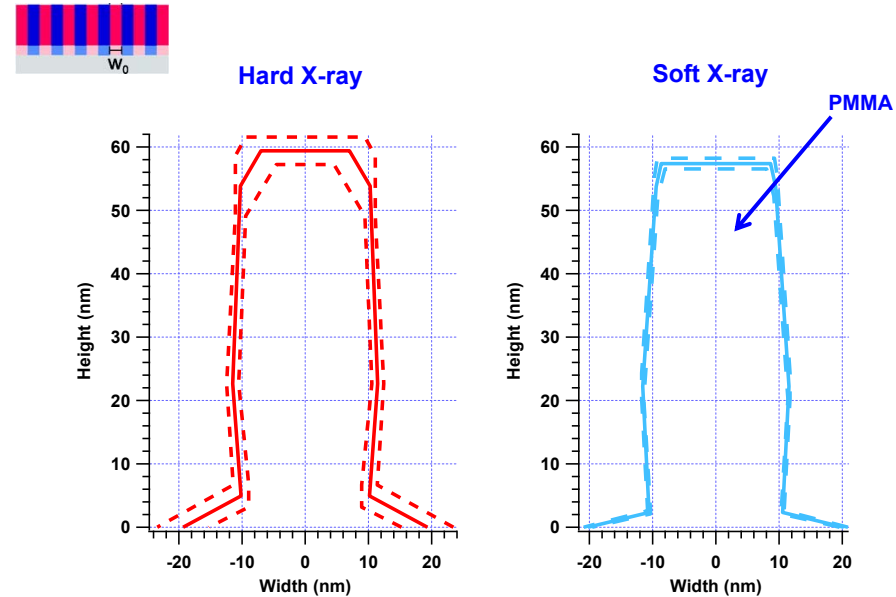
3: Measurement of electrons and chemistry

RSoXS: soft-x-ray potential for 3D chemically sensitive profile metrology

CD-RSoXS on Polymer Lithography Grating



Sunday et al. **JM3** 12 (3), 2013, 031103



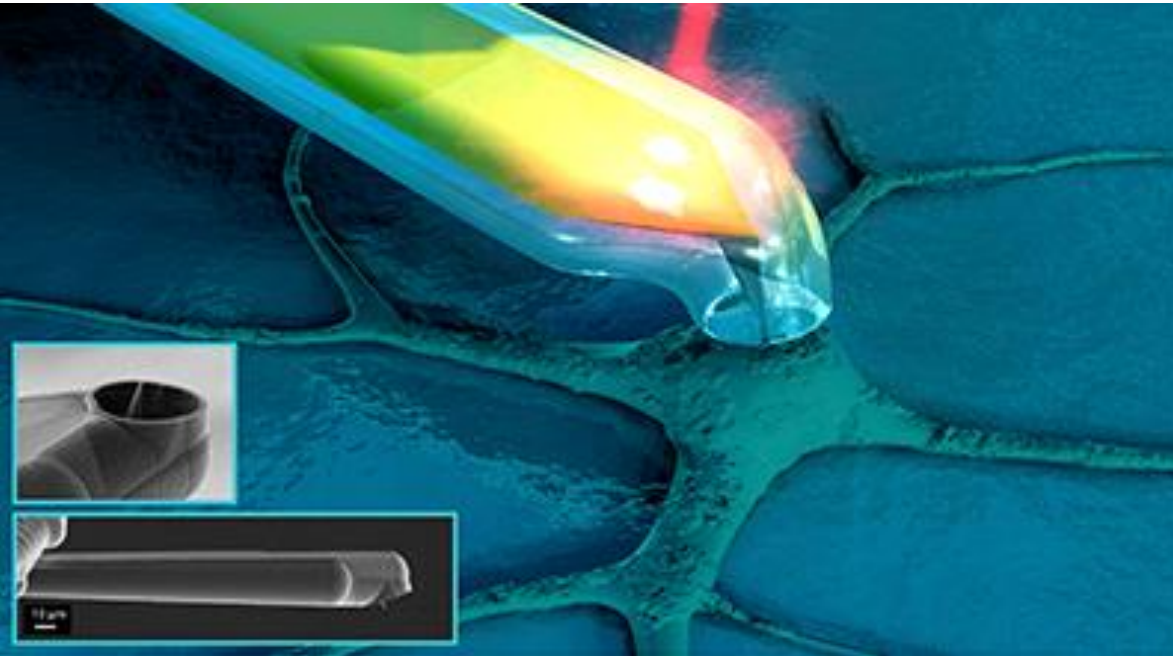
Compares favorably to hard X-ray and provides benefit of chemical sensitivity for potential use in latent images



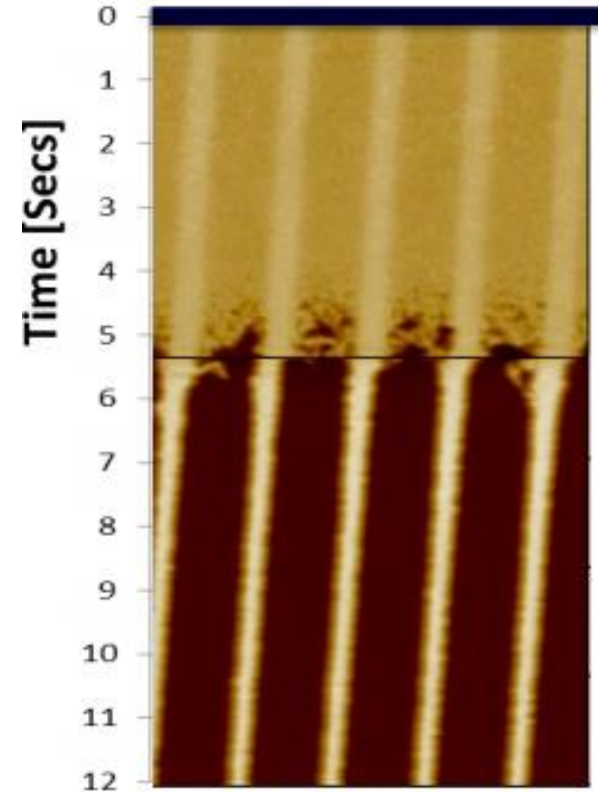
A. Hexemer

Realtime in liquid AFM for development studies

Encased cantilever for fast response in liquid



Start of developer injection

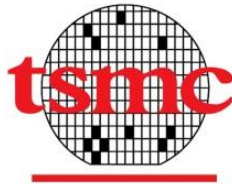


JSR1099

Acknowledgements

Eric Panning, Intel
Seong-Sue Kim, Samsung
Tony Yen, TSMC
Andrew Grenville, Inpria
Marc Slezak, JSR
Ellie Yieh, AMAT
Greg Wallraff, IBM

Chris Anderson, LBNL
Markus Benk, LBNL
Weilun Chao, LBNL
Ken Goldberg, LBNL
Eric Gullikson, LBNL
Ryan Miyakawa, LBNL
Seno Rekawa, LBNL
Antoine Wojdyla, LBNL



CXRO

